



DECLARATION UNDER C.F.R. §1.131

I, Peter Hartwell, employee of the Hewlett-Packard Company, am the inventor of the subject matter disclosed in U.S. Patent Application 10/822,413 (the "413 application") based on U.S. Patent Application 10/035,792 (the "792 application").

2. I conceived the subject matter of the "792 application in the United States at least as early as August 3, 2000, on which date I filled out an invention disclosure form of the Hewlett-Packard Company, a copy of which is attached hereto as Exhibit A.

3. Upon information and belief, the invention disclosure form that described the subject matter of the '792 application was provided to the Hewlett-Packard legal department for the purpose of determining whether a patent application should be pursued.

4. Upon information and belief, the Hewlett-Packard legal department regularly and periodically reviews invention disclosure forms that are submitted for the purpose of determining whether patent applications should be prepared and filed.

5. Upon information and belief, it was determined that a patent application should be prepared and filed based upon our invention disclosure and that the invention disclosure was referred to outside counsel for preparation of a patent application.

6. Upon information and belief, on or about October 16, 2000, Paul Qualey, Esquire, was sent a copy of the invention disclosure under cover letter of October 16, 2000 (Exhibit B), and was requested to prepare a U.S. patent application based upon the subject matter included therein.

7. Mr. Qualey corresponded with me and prepared a draft application for my review. I approved the final draft of the application by August 21, 2001.

8. Upon information and belief, on August 21, 2001 a copy of the final application was forwarded to the Hewlett-Packard Company for filing with the U.S. Patent and Trademark Office (U.S.P.T.O.).

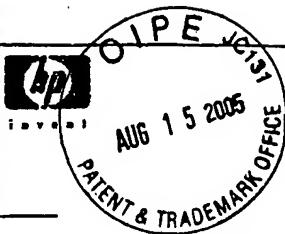
9. Upon information and belief, the patent application that is now identified as the '792 application was filed with the U.S.P.T.O. on October 18, 2001. The divisional application (the '413 application), filed on April 12, 2004, claims priority to the '792 application.

I hereby declare: (a) that all statements made herein of my own knowledge are true; (b) that all statements made on information and belief are believed to be true; (c) that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code; and (d) that such willful false statements may jeopardize the validity of the application or any patent issued thereon.


Peter G. Hartwell
Date: 8/11/2005

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INVENTION DISCLOSURE

PAGE ONE OF

PDNO

10006166

DATE RCVD

8-3-00

ATTORNEY

MSB
AJB

Instructions: The information contained in this document is COMPANY CONFIDENTIAL and may not be disclosed to others without prior authorization. Submit this disclosure to the HP Legal Department as soon as possible. No patent protection is possible until a patent application is authorized, prepared, and submitted to the Government.

Descriptive Title of Invention:

DEEP TRENCH Isolation of Large Substrate Areas

Name of Project:

Product Name or Number:

Was a description of the invention published, or are you planning to publish? If so, the date(s) and publication(s):

Was a product including the invention announced, offered for sale, sold, or is such activity proposed? If so, the date(s) and location(s):

Was the invention disclosed to anyone outside of HP, or will such disclosure occur? If so, the date(s) and name(s):

If any of the above situations will occur within 3 months, call your IP attorney or the Legal Department now at 1-898-4919 or 970-898-4919.

Was the invention described in a lab book or other record? If so, please identify (lab book #, etc.)

Was the invention built or tested? If so, the date:

Was this invention made under a government contract? If so, the agency and contract number:

Description of Invention: Please preserve all records of the invention and attach additional pages for the following. Each additional page should be signed and dated by the inventor(s) and witness(es).

- A. Description of the construction and operation of the invention (include appropriate schematic, block, & timing diagrams; drawings; samples; graph flowcharts; computer listings; test results; etc.)
- B. Advantages of the invention over what has been done before.
- C. Problems solved by the invention.
- D. Prior solutions and their disadvantages (if available, attach copies of product literature, technical articles, patents, etc.).

EXHIBIT A
PAGE 1 OF 4

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Signature of Inventor(s): Pursuant to my (our) employment agreement, I (we) submit this disclosure on this date: [].				
Employee No.	PETER HARTWELL	Peter A Hartwell Signature	8573748 20-20	0419-5213
Employee No.	Name	Signature	Telnet Mailstop	Entity & Lab Name
Employee No.	Name	Signature	Telnet Mailstop	Entity & Lab Name
Employee No.	Name	Signature	Telnet Mailstop	Entity & Lab Name
(If more than four inventors, include additional information on another copy of this form and attach to this document)				

O I P E JC131
AUG 15 2005

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INVENTION DISCLOSURE

COMPANY CONFIDENTIAL

PAGE ____ OF ____

Signature of Witness(es) (Please try to obtain the signature of the person(s) to whom invention was first disclosed.)

The invention was first explained to, and understood by, me (us) on this date: []

Full Name

Signature

Date of Signature

Full Name

Signature

Date of Signature

Inventor & Home Address Information: (If more than four inventors, include add'l. information on a copy of this form & attach to this document)

Inventor's Full Name

PETER GEORGE HARTWELL

Street

City

State

Zip

Do you have a Residential P.O. Address? P.O. BOX

City

State

Zip

Greeted as (nickname, middle name, etc.)

Citizenship

Inventor's Full Name

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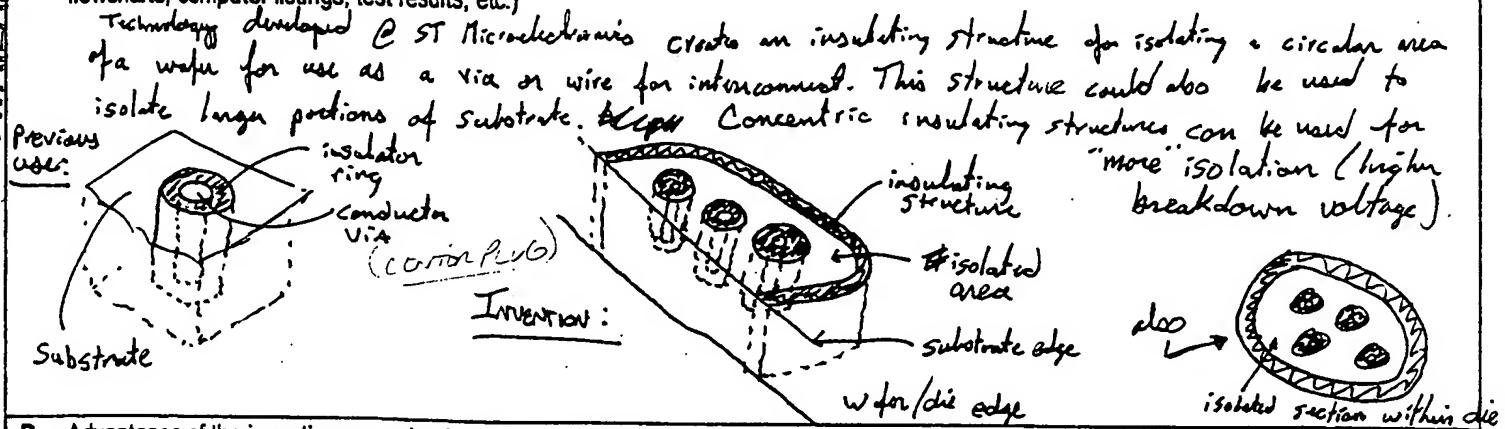
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Description of Invention: Please preserve all records of the invention and attach additional pages for the following. Each additional page should be signed and dated by the inventor(s) and witness(es).

A. Description of the construction and operation of the invention (include appropriate schematic, block, & timing diagrams; drawings; samples; graph flowcharts; computer listings; test results; etc.)



B. Advantages of the invention over what has been done before.

Implementation of high voltage conductors on substrates creates problems of breakdown (shorting) when substrate is at ground or other large potential difference. Isolating portions of the substrate using invention can eliminate this problem in a large area for many conductors all at one time.

④ Concentric Rings

C. Problems solved by the invention.

Signal isolation for high voltage lines from substrate.

Signal isolation for lowering background noise levels.

D. Prior solutions and their disadvantages (if available, attach copies of product literature, technical articles, patents, etc.).

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IP ATTORNEY

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October 16, 2000

Paul Qualey
Thomas, Kayden, Horstemeyer & Risley L.L.P
100 Galleria Parkway NW
Suite 1750
Atlanta GA 30339-5948

50818-1380

RE: Preparation of Patent Application

Pursuant to Outside Counsel Procedures Dated October 15, 1999

HP Reference No.: 10006166.

Entitled: Deep Trench Isolation Of Large Substrate Areas

HP Required Date: March 23, 2001

DOCKETED

Dear Paul:

We would like you to provide a quote of the cost for your firm to prepare a US Patent application based on the HP Invention Disclosure identified above, a copy of which is enclosed.

Your quote should be based on preparing an application including the items noted on the enclosed Outside Counsel Checklist and according to HP's Outside Counsel Procedures referenced above, for filing by our Required Date.

Your quote should be submitted on the enclosed Request for Quote and Engagement Letter Agreement. If your quote is accepted, we will return a fully executed copy of the Agreement to you for your records. **The Agreement will not be binding on you or on HP until signed by HP's authorized representative.**

If the Agreement is not signed and returned to HP, any bills submitted by you cannot be paid.

Thank you for your assistance in reviewing this invention disclosure. If your review indicates a possible conflict for your firm, you should advise us within one week of receipt of this letter.

Sincerely,

Steven R. Ormiston (cg)

Steven R. Ormiston

Enc.: HP Invention Disclosure
RFQ
Outside Counsel Checklist

EXHIBIT B
PAGE 1 OF 1